2-Input Exclusive OR Gate / **CMOS Logic Level Shifter**

with LSTTL-Compatible Inputs

The MC74VHC1GT86 is an advanced high speed CMOS 2-input Exclusive OR gate fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing. The input protection circuitry on this device allows overvoltage tolerance on the input, allowing the device to be used as a logic-level translator from 3.0 V CMOS logic to 5.0 V CMOS Logic or from 1.8 V CMOS logic to 3.0 V CMOS Logic while operating at the high-voltage power supply.

The MC74VHC1GT86 input structure provides protection when voltages up to 7.0 V are applied, regardless of the supply voltage. This allows the MC74VHC1GT86 to be used to interface 5.0 V circuits to 3.0 V circuits. The output structures also provide protection when V_{CC} = 0 V. These input and output structures help prevent device destruction caused by supply voltage - input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- High Speed: $t_{PD} = 4.8 \text{ ns}$ (Typ) at $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A \text{ (Max)}$ at $T_A = 25 \text{°C}$
- TTL-Compatible Inputs: $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$
- CMOS–Compatible Outputs: $V_{OH} > 0.8 V_{CC}$; $V_{OL} < 0.1 V_{CC}$ @Load
- Power Down Protection Provided on Inputs and Outputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 83; Equivalent Gates = 16
- Pb-Free Packages are Available

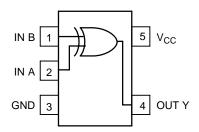


Figure 1. Pinout (Top View)

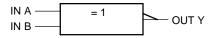


Figure 2. Logic Symbol



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MARKING DIAGRAMS

SC-88A / SOT-353 / SC-70 **DF SUFFIX CASE 419A**



TSOP-5 / SOT-23 / SC-59 **DT SUFFIX CASE 483**



= Date Code

= Assembly Location \/\/\/ = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT				
1	IN B			
2	IN A			
3	GND			
4	OUT Y			
5	V _{CC}			

FUNCTION TABLE

Inp	uts	Output
Α	В	Υ
L	L	L
L	Н	Н
н	L	Н
Н	Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage $V_{CC} = 0$ High or Low State	−0.5 to 7.0 −0.5 to V _{CC} + 0.5	V
I _{IK}	Input Diode Current	-20	mA
I _{OK}	Output Diode Current $V_{OUT} < GND; V_{OUT} > V_{CC}$	+20	mA
I _{OUT}	DC Output Current, per Pin	+25	mA
I _{CC}	DC Supply Current, V _{CC} and GND	+50	mA
P_{D}	Power dissipation in still air SC-88A, TSOP-5	200	mW
θ_{JA}	Thermal resistance SC–88A, TSOP–5	333	°C/W
TL	Lead temperature, 1 mm from case for 10 s	260	°C
TJ	Junction temperature under bias	+150	°C
T _{stg}	Storage temperature	-65 to +150	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 5)	±500	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. Derating SC–88A Package: –3 mW/°C from 65° to 125°C
 TSOP5 Package: –3 mW/°C from 65° to 125°C
 2. Tested to EIA/JESD22–A114–A
- 3. Tested to EIA/JESD22-A115-A
- Tested to JESD22-C101-A
- 5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	DC Supply Voltage	3.0	5.5	V
V_{IN}	DC Input Voltage	0.0	5.5	V
V _{OUT}	DC Output Voltage $V_{CC} = 0$ High or Low State	0.0 0.0	5.5 V _{CC}	V
T _A	Operating Temperature Range	-55	+125	°C
t _r , t _f	Input Rise and Fall Time $ \begin{array}{c} \rm V_{CC} = 3.3~V \pm 0.3~V \\ \rm V_{CC} = 5.0~V \pm 0.5~V \\ \end{array} $	0	100 20	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

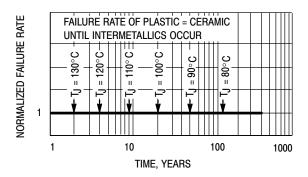


Figure 3. Failure Rate vs. Time **Junction Temperature**

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	1	A = 25°(С	T _A ≤	85°C	-55 ≤ T _A	-55 ≤ T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		3.0 4.5 5.5	1.4 2.0 2.0			1.4 2.0 2.0		1.4 2.0 2.0		V
V _{IL}	Maximum Low-Level Input Voltage		3.0 4.5 5.5			0.53 0.8 0.8		0.53 0.8 0.8		0.53 0.8 0.8	V
V _{OH}	Minimum High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
	$V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V _{OL}	Maximum Low–Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu A$	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	V
	$V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
I _{IN}	Maximum Input Leakage Current	$V_{IN} = 5.5 \text{ V or GND}$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μΑ
I _{CCT}	Quiescent Supply Current	Input: V _{IN} = 3.4 V	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0.0			0.5		5.0		10	μΑ

AC ELECTRICAL CHARACTERISTICS C_{load} = 50 pF, Input t_r = t_f = 3.0 ns

•					T _A = 25°C		T _A ≤	85°C	-55 ≤ T _A	≤ 125°C	·
Symbol	Parameter	Test Condit	tions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay,	$V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 15 pF$ $C_L = 50 pF$		5.0 6.2	11.0 14.5		13.0 16.5		15.5 19.5	ns
	Input A or B to Y	$V_{CC} = 5.0 \pm 0.5 \text{ V}$	$C_L = 15 pF$ $C_L = 50 pF$		3.1 4.2	6.8 8.8		8.0 10.0		10.0 12.0	
C _{IN}	Maximum Input Capacitance				5.5	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Note 6)	11	pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

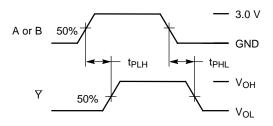
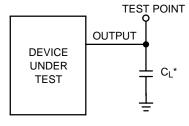


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance

Figure 5. Test Circuit

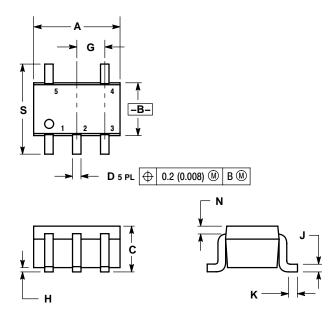
DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size [†]
MC74VHC1GT86DFT1	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1GT86DF1G	SC-88A / SOT-353 / SC-70 (Pb-Free)	178 mm (7") 3000 Unit
MC74VHC1GT86DFT2	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1GT86DF2G	SC-88A / SOT-353 / SC-70 (Pb-Free)	178 mm (7") 3000 Unit
MC74VHC1GT86DTT1	TSOPS / SOT-23 / SC-59	178 mm (7") 3000 Unit
MC74VHC1GT86DT1G	TSOPS / SOT-23 / SC-59 (Pb-Free)	178 mm (7") 3000 Unit

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88A/SOT-353/SC-70 CASE 419A-02 **ISSUE H**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

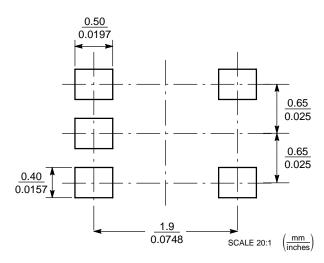
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN MAX		MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
H		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004 0.012		0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

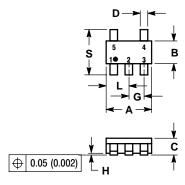
SOLDERING FOOTPRINT*

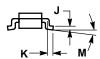


*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-5/SOT-23/SC-59 CASE 483-02 ISSUE D



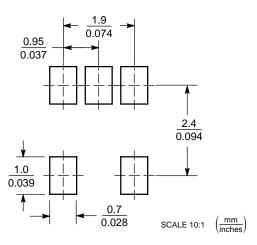


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
C	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
ſ	0.10	0.26	0.0040	0.0102
Κ	0.20	0.60	0.0079	0.0236
٦	1.25	1.55	0.0493	0.0610
М	0 °	10°	0°	10°
S	2.50	3.00	0.0985	0.1181

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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